Product Change Notification: DSNO-11MVVE817

Date:

28-Sep-2026

Product Category:

Ethernet Controllers, Ethernet Phys

Notification Subject:

CCB 7987 Final Notice: Qualification of ANAP as an additional assembly site for KSZ8081MLXCA, KSZ8091MLXCA, KSZ8081MLXIA, KSZ8091MLXIA, KSZ8081MLXCA-TR, KSZ8091MLXCA-TR, KSZ8081MLXIA-TR, KSZ8041MLL, KSZ8041MLLI, KSZ8041MLL-TR, KSZ8041MLLI-TR, KSZ8851-16MLL, KSZ8851-16MLLI, KSZ8851-16MLL-TR, KSZ8851-16MLLI-TR and SPNY801088-TR catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package.

Affected CPNs:

DSNO-11MVVE817_Affected_CPN_09282026.pdf
DSNO-11MVVE817_Affected_CPN_09282026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ANAP as an additional assembly site for KSZ8081MLXCA, KSZ8091MLXCA, KSZ8081MLXIA, KSZ8091MLXIA, KSZ8081MLXCA-TR, KSZ8091MLXCA-TR, KSZ8081MLXIA-TR, KSZ8041MLL, KSZ8041MLLI, KSZ8041MLL-TR, KSZ8041MLLI-TR, KSZ8851-16MLL, KSZ8851-16MLLI, KSZ8851-16MLL-TR, KSZ8851-16MLLI-TR and SPNY801088-TR catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)

Assembly Site	ASE Inc. (ASE)		ASE Inc. (ASE)		Amkor Technology Philippine (P1/P2), Inc. (ANAP)	Yes
Wire Material	Au	CuPdAu	Au	CuPdAu	CuPdAu	Yes
Die Attach Material	EN-4900F (PFAS)	CRM-1076WA (PFAS)	EN-4900F (PFAS)	CRM-1076WA (PFAS)	3230 (PFAS-Free)	Yes
Molding Compound Material	G631		G631		G631	No
Lead-Frame Material	C7025		C7025		C194	Yes
Lead-Frame Paddle Size	197x197mils	150x150mils	197x197mils	150x150mils	197x197mils	No
Lead-Frame Design	See Pre and Post Change Summary attachment for comparison.					

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ANAP as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 04 November 2026 (date code: 2645)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	December 2025				>	September 2026					>	November 2026			
Work Week	49	50	51	52		36	37	38	39	40		45	46	47	48
Initial PCN Issue Date			x												

Qual Report Availability										**x**					
Final PCN Issue Date										**x**					
Estimated Implementation Date												x			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

December 15, 2025: Issued initial notification.
December 22, 2025: Re-issued initial notification to update post-change wire bond material for ASE and ANAP.
September 28, 2026: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on November 04, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-11MVVE817_Pre and_Post Change_Summary.pdf
PFAS Elimination and Die Attach_Explanation.pdf
PCN_DSNO-11MVVE817 Qual Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

KSZ8041MLL

KSZ8041MLLI

KSZ8041MLL-TR

KSZ8041MLLI-TR

KSZ8851-16MLL

KSZ8851-16MLLI

KSZ8851-16MLL-TR

KSZ8851-16MLLI-TR

SPNY801088-TR

KSZ8081MLXCA

KSZ8091MLXCA

KSZ8081MLXIA

KSZ8091MLXIA

KSZ8081MLXCA-TR

KSZ8091MLXCA-TR

KSZ8081MLXIA-TR



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: DSNO-11MVVE817

Date

July 14, 2026

Qualification of ANAP as an additional assembly site for KSZ8081MLXCA, KSZ8091MLXCA, KSZ8081MLXIA, KSZ8091MLXIA, KSZ8081MLXCA-TR, KSZ8091MLXCA-TR, KSZ8081MLXIA-TR, KSZ8041MLL, KSZ8041MLLI, KSZ8041MLL-TR, KSZ8041MLLI-TR, KSZ8851-16MLL, KSZ8851-16MLLI, KSZ8851-16MLL-TR, KSZ8851-16MLLI-TR and SPNY801088-TR catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of ANAP as an additional assembly site for KSZ8081MLXCA, KSZ8091MLXCA, KSZ8081MLXIA, KSZ8091MLXIA, KSZ8081MLXCA-TR, KSZ8091MLXCA-TR, KSZ8081MLXIA-TR, KSZ8041MLL, KSZ8041MLLI, KSZ8041MLL-TR, KSZ8041MLLI-TR, KSZ8851-16MLL, KSZ8851-16MLLI, KSZ8851-16MLL-TR, KSZ8851-16MLLI-TR and SPNY801088-TR catalog part numbers (CPN) available in 48L LQFP (7x7x1.4mm) package.

Assembly Site:	ANAP
MP CODE:	TKDB1TCAAA01
Part No.:	KSZ8851-1 6MLLI-TR
MSL Information:	MSL-3, 260'C
Assembly Shipping Media (T/R, Tube/Tray):	Tray
Base Quantity Multiple (BQM):	250 / 1,000
Reliability Site:	MTAI
Bonding No.:	BD-004001
CCB No.:	7987

Lead Frame

Paddle Size:	197x197mils
Material:	C194
DAP Surface Prep:	Double Ring Ag
Treatment:	Non Rough
Process:	Stamp
Lead Lock:	No
Part Number:	101387387
Lead Plating:	MatteSn
Strip Size:	250 x 70
Strip Density:	90

Bond Wire

Wire:	CuPdAu wire

Die Attach Material

Epoxy:	3230
Conductive:	Yes

Mold Compound

Mold Compound:	G631HQ

Package

Package Type:	LQFP
Pin/Ball Count:	48
Package Width/Size:	7x7x1.4mm

Manufacturing Information

Assembly Lot No.
ANAP264400048.000
ANAP264400049.000
ANAP264400050.000

Result: **Pass**

Conclusion:

TKDB1TCAAA01 in 48L LQFP 7x7x1.4mm Package assembled at ANAP pass reliability test that was conducted at MPHL rel lab. This package is qualified Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Moisture Soak Precondition Prior to Stresses	**MSL3:** 150°C 24-hour Bake 192 hour moisture soak at 30°C/60%RH. 3x Reflow at 260°C max.	JESD22-A113 ; IPC/JEDEC J-STD-020	231 / 3 lots	0/231	Pass	Electrical test at Chroma/SMB600.
High Temp Storage	175 C for 504 hours	JESD22-A103	45 / 3 Lot	0/135	Pass	Electrical test at Chroma/SMB600.
Temperature Cycling	-65°C to +150°C Air to Air / 500 Cycles	JESD22-A104	77 each lot / 3 lots	0/231	Pass	Electrical test at Chroma/SMB600.
	WBP		-	0/5	Pass	
HAST	+130°C / 85% RH / 96 hours	JESD22-A110	77 each lot / 3 lots	0/231	Pass	Electrical test at Chroma/SMB600.
Unbiased HAST	+130°C / 85% RH / 96 hours	JESD22-A118	77 each lot / 3 lots	0/231	Pass	Electrical test at Chroma/SMB600.
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8-hr steam age. Dip at 245C. 100% leads >95% lead coverage.	J-STD-002 / JESD22B-102	22 / 1 lot	0/22	Pass	ANAP264400050.000
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	10 units / 3 lots		Pass	

CCB 7987
Pre and Post Change Summary
PCN #: DSNO-11MVVE817

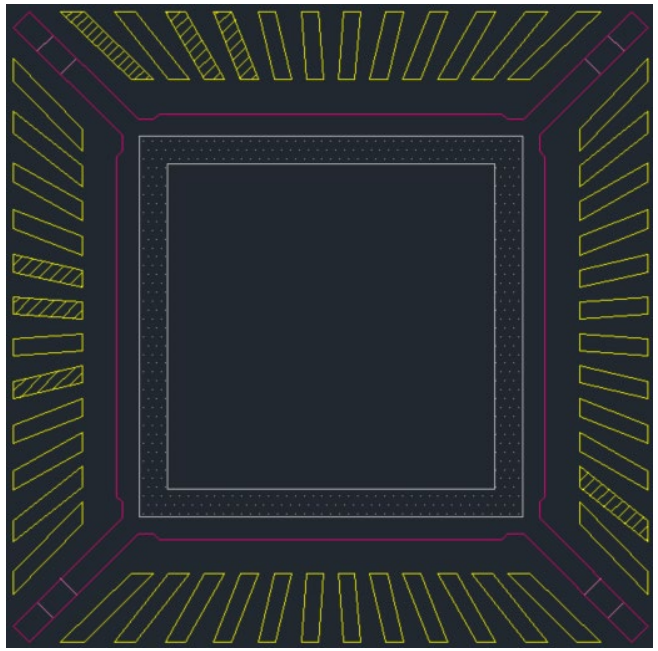


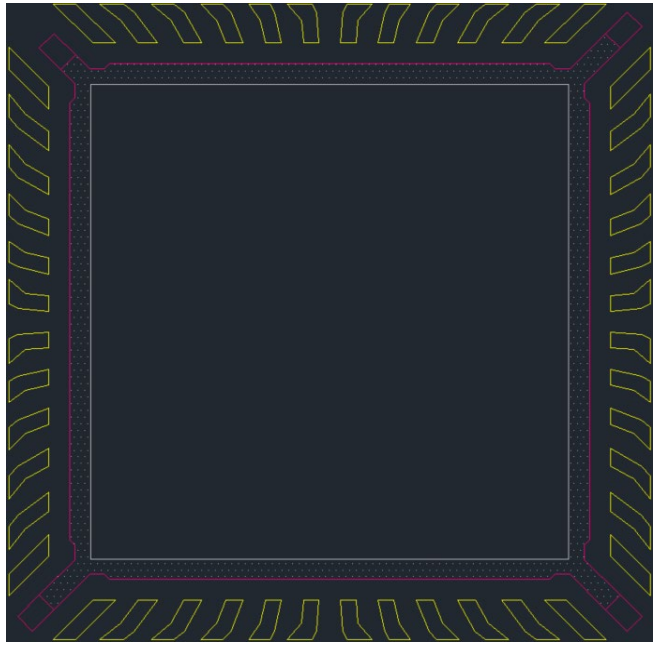
A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



Lead-Frame Comparison

ASE

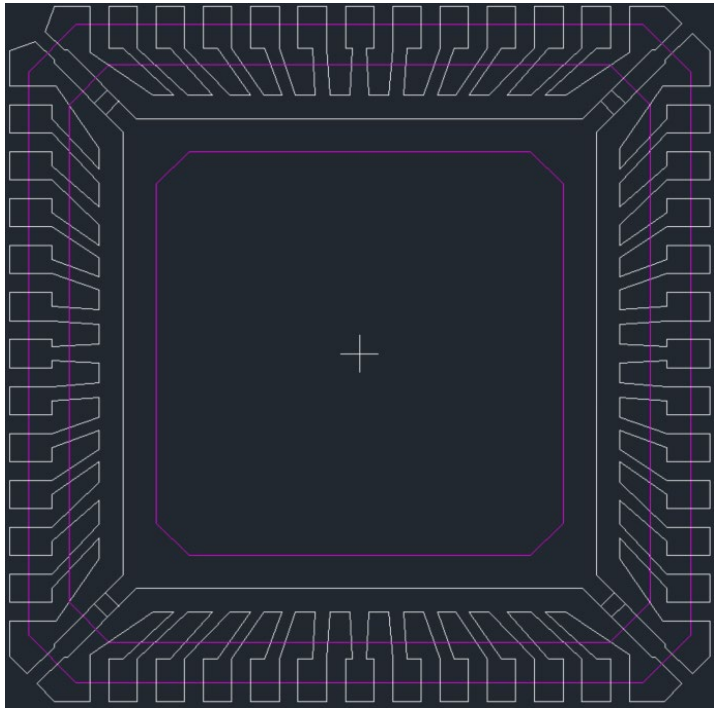




Note: Not to scale

Lead-Frame Material	C7025	
Lead-Frame Paddle Size	197x197mils	150x150mils

ANAP



Note: Not to scale

Lead-Frame Material	C194
Lead-Frame Paddle Size	197x197mils

MICROCHIP

Eliminating PFAS from Microchip ICs



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



Microchip

August 2025

Eliminating PFAS from MCHP ICs

- What is PFAS
- Microchip's Environmental Stewardship
- Microchip Products with PFAS
- Time Frame to PFAS-Free Die Attach
- What is Die Attach
- Will clients be required to switch to PFAS free products
- Risk Assessment

What is PFAS: Poly(Per) FluoroAlkyl Substances (PFAS)

Poly(Per) FluoroAlkyl Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
  - PFAS can be in the product itself.
  - PFAS can also be used to manufacture products while not in the product itself

PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet

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Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

Achieving "PFAS-Free" status may serve as a competitive advantage for both Microchip and its clients.

Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

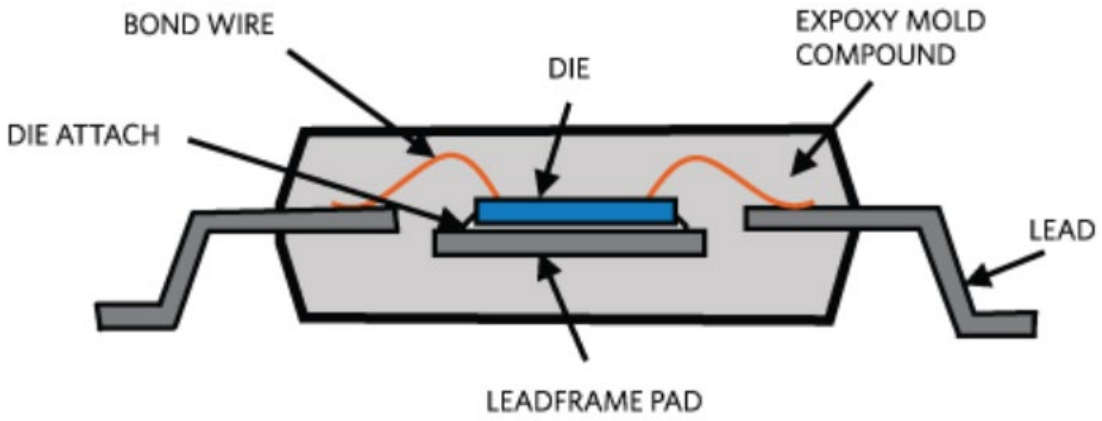
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

What is die attach



A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**

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Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.



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